ABSTRACT OF THE DISCLOSURE

In a wafer, a plurality of basic chips F is arranged therein. The basic chip F has a memory capacity of i-mega bytes. By dicing, a memory chip including four basic chips F is cut out of the wafer. The memory chip has a memory capacity of 4 x i-mega bytes. A dicing line is interposed between four basic chips F configuring the memory chip, Four basic chips F can change word organization by a control signal individually.